

Designation: E722 – 09

Standard Practice for Characterizing Neutron Fluence Spectra in Terms of an Equivalent Monoenergetic Neutron Fluence for Radiation-Hardness Testing of Electronics¹

This standard is issued under the fixed designation E722; the number immediately following the designation indicates the year of original adoption or, in the case of revision, the year of last revision. A number in parentheses indicates the year of last reapproval. A superscript epsilon (ε) indicates an editorial change since the last revision or reapproval.

This standard has been approved for use by agencies of the Department of Defense.

1. Scope

1.1 This practice covers procedures for characterizing neutron fluence from a source in terms of an equivalent monoenergetic neutron fluence. It is applicable to neutron effects testing, to the development of test specifications, and to the characterization of neutron test environments. The sources may have a broad neutron-energy range, or may be mono-energetic neutron sources with energies up to 20 MeV. This practice is not applicable in cases where the predominant source of displacement damage is from neutrons of energy less than 10 keV. The relevant equivalence is in terms of a specified effect on certain physical properties of materials upon which the source spectrum is incident. In order to achieve this, knowledge of the effects of neutrons as a function of energy on the specific property of the material of interest is required. Sharp variations in the effects with neutron energy may limit the usefulness of this practice in the case of mono-energetic sources.

1.2 This practice is presented in a manner to be of general application to a variety of materials and sources. Correlation between displacements $(1-3)^2$ caused by different particles (electrons, neutrons, protons, and heavy ions) is beyond the scope of this practice. In radiation-hardness testing of electronic semiconductor devices, specific materials of interest include silicon and gallium arsenide, and the neutron sources generally are test and research reactors and californium-252 irradiators.

1.3 The technique involved relies on the following factors: (1) a detailed determination of the fluence spectrum of the neutron source, and (2) a knowledge of the degradation (damage) effects of neutrons as a function of energy on specific material properties.

1.4 The detailed determination of the neutron fluence spectrum referred to in 1.3 need not be performed afresh for each test exposure, provided the exposure conditions are repeatable. When the spectrum determination is not repeated, a neutron fluence monitor shall be used for each test exposure.

1.5 The values stated in SI units are to be regarded as standard. No other units of measurement are included in this standard.

1.6 This standard does not purport to address all of the safety concerns, if any, associated with its use. It is the responsibility of the user of this standard to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use.

2. Referenced Documents

- 2.1 ASTM Standards:³
- E170 Terminology Relating to Radiation Measurements and Dosimetry
- E265 Test Method for Measuring Reaction Rates and Fast-Neutron Fluences by Radioactivation of Sulfur-32
- E693 Practice for Characterizing Neutron Exposures in Iron and Low Alloy Steels in Terms of Displacements Per Atom (DPA), E 706(ID)
- E720 Guide for Selection and Use of Neutron Sensors for Determining Neutron Spectra Employed in Radiation-Hardness Testing of Electronics
- E721 Guide for Determining Neutron Energy Spectra from Neutron Sensors for Radiation-Hardness Testing of Electronics
- E844 Guide for Sensor Set Design and Irradiation for Reactor Surveillance, E 706(IIC)
- **E944** Guide for Application of Neutron Spectrum Adjustment Methods in Reactor Surveillance, E 706 (IIA)

2.2 International Commission on Radiation Units and Measurements (ICRU) Reports:

¹ This practice is under the jurisdiction of ASTM Committee E10 on Nuclear Technology and Applications and is the direct responsibility of Subcommittee E10.07 on Radiation Dosimetry for Radiation Effects on Materials and Devices.

Current edition approved June 1, 2009. Published August 2009. Originally approved in 1980. Last previous edition approved in 2004 as $E722 - 04^{e2}$. DOI: 10.1520/E0722-09.

 $^{^{2}}$ The boldface numbers in parentheses refer to a list of references at the end of this practice.

³ For referenced ASTM standards, visit the ASTM website, www.astm.org, or contact ASTM Customer Service at service@astm.org. For *Annual Book of ASTM Standards* volume information, refer to the standard's Document Summary page on the ASTM website.

Copyright © ASTM International, 100 Barr Harbor Drive, PO Box C700, West Conshohocken, PA 19428-2959, United States.

ICRU Report 13—Neutron Fluence, Neutron Spectra, and Kerma⁴

ICRU Report 26—Neutron Dosimetry for Biology and Medicine⁴

ICRU Report 33-Radiation Quantities and Units⁴

3. Terminology

3.1 Definitions of Terms Specific to This Standard:

3.1.1 *displacement damage function*—($F_{D,mat}$) an energydependent parameter proportional to the quotient of the observable displacement damage per target atom and the neutron fluence. Different displacement-related damage functions may exist, so the damage mode of interest and the observation procedure shall be identified when the specific damage function is defined. See, for example, Annexes A1.2.2 and A2.2.2.

3.1.1.1 Discussion-Observable changes in a material's properties attributable to the atomic displacement process are useful indices of displacement damage in that material. In cases where the observed displacement damage is not in linear proportion to the applied fluence, the displacement damage function represents the quotient $F_{D,mat}$ (E)/d Φ , in the limiting case of zero fluence. Examples of suitable representations of displacement damage functions are given in the annexes. In the case of silicon, damage mode of interest is the change in minority-carrier recombination lifetime in the bulk semiconductor material. While several procedures exist to directly measure the minority carrier lifetime in bulk material, since this lifetime is related to the gain of a bipolar junction transistor (BJT), one observable damage metric is the BJT gain degradation. For this damage mode, it has been shown that the displacement damage function may be successfully equated with the microscopic displacement kerma factor. This question is discussed further in the annexes.

3.1.2 microscopic displacement kerma factor— $(K_{D,mat} (E))$ the energy-dependent quotient of the displacement kerma per target atom and the neutron fluence. $K_{D,mat} (E)$ is proportional to $K_{D,mat}$. \bar{A}/Φ , where $K_{D,mat}$ is the displacement kerma, \bar{A} is the mean atomic mass of the material and Φ is the neutron fluence from a monoenergetic source of energy E.

3.1.2.1 *Discussion*—This quantity may be calculated from the microscopic neutron interaction cross sections, the kinematic relations for each reaction and from a suitable partition function which divides the total kerma into ionization and displacement kerma. The use of the term *microscopic* kerma factor in this standard is to indicate that energy times area per atom is used, instead of per unit mass, as in the term kerma factor defined in E170.

3.1.3 fluence spectrum hardness parameter—(H $_{mat} = \Phi_{eq,Eref,mat}/\Phi$) this parameter is defined as the ratio of the equivalent monoenergetic neutron fluence to the total fluence, $\Phi_{eq,Eref,mat}/\Phi$. The numerical value of the hardness parameter is also equal to the fluence of monoenergetic neutrons at the specific energy, Eref, required to produce the same displacement damage in the specified material, mat, per unit fluence of neutrons of neutron spectrum $\Phi(E)$.

3.1.3.1 *Discussion*—For damage correlation, a convenient method of characterizing the shape of an incident neutron fluence spectrum $\Phi(E)$, is in terms of a fluence spectrum hardness parameter. The hardness parameter in a particular neutron field depends on the displacement damage function used to compute the damage (see annexes) and is therefore different for different semiconductor materials.

3.1.4 equivalent monoenergetic neutron fluence— ($\Phi_{eq,Eref}$, mat) an equivalent monoenergetic neutron fluence, $\Phi_{eq,Eref}$, mat) an equivalent monoenergetic neutron fluence, $\Phi_{eq,Eref,mat}$, characterizes an incident fluence spectrum, $\Phi(E)$, in terms of the fluence of monoenergetic neutrons at a specific energy Eref required to produce the same displacement damage in a specified irradiated material, mat, as $\Phi(E)$.

3.1.4.1 Discussion—Note that $\Phi_{eq,Eref,mat}$ is equivalent to $\Phi(E)$ if, and only if, the specific device effect (for example, current gain degradation in silicon) being correlated is described by the displacement damage function used in the calculation.

3.1.5 *fluence* and *fluence spectrum*—see *neutron fluence* and *neutron fluence spectrum*.

3.1.6 *kerma factor*—(K_{mat} (E)) the **kerma** per unit fluence of particles of energy E present in a specified material, mat. See Terminology E170 for the definition of **kerma**, and a formula for calculating the kerma factor.

3.1.6.1 *Discussion*—When a material is irradiated by a neutron field, the energy imparted to charged particles in the material may be described by the kerma. The kerma may be divided into two parts, ionization kerma and displacement kerma. See 3.1.2.1 for the distinction between kerma factor and microscopic kerma factor. Calculations of ionization and microscopic displacement kerma in silicon and gallium arsenide as a result of irradiation by neutrons with energies up to 20 MeV are described in Refs **5-8** and in the annexes.

3.1.7 *neutron fluence* and *neutron fluence spectrum* are used in this standard, and are special cases of **particle fluence** and **particle fluence spectrum** as defined in E170.

3.1.7.1 *Discussion*—In cases where the context makes clear that neutrons are referred to, the terms *fluence* and *fluence spectrum* are sometimes used.

4. Summary of Practice

4.1 The equivalent monoenergetic neutron fluence, $\Phi_{eq,Eref,mat}$, is given as follows:

$$\Phi_{\rm eq, Eref, mat} = \frac{\int_{0}^{\infty} \Phi(E) F_{\rm D, mat}(E) dE}{F_{\rm D, Eref, mat}}$$
(1)

where: $\Phi(E)$

F_{D.mat}

= incident neutron fluence spectrum,

- neutron displacement damage function for the irradiated material (displacement damage per unit fluence) as a function of energy, and
- F_{D,Eref,mat} = displacement damage reference value designated for the irradiated material and for the specified equivalent energy, Eref, as given in the annexes.

⁴ Available from International Commission on Radiation Units and Measurements, 7910 Woodmont Avenue Suite 400 Bethesda, MD 20841-3095, http:// www.icru.org/

The energy limits on the integral are determined in practice by the incident neutron fluence spectrum and by the material being irradiated.

4.2 The neutron spectrum hardness parameter, $\rm H_{mat},$ is given as follows:

$$H_{mat} = \frac{\int_{0}^{\infty} \Phi(E) F_{D,mat}(E) dE}{F_{D,Eref,mat} \int_{0}^{\infty} \Phi(E) dE}$$
(2)

4.3 Once the neutron fluence spectrum has been determined (for example, in accordance with Test Method E721) and the equivalent monoenergetic fluence calculated, then a monitor (such as an activation foil) can be used in subsequent irradiations at the same location to determine the fluence; that is, the neutron fluence is then described in terms of the equivalent monoenergetic neutron fluence per unit monitor response, $\Phi_{eq,Eref,mat}/M_r$. Use of a monitor foil to predict $\Phi_{eq,Eref,mat}$ is valid only if the neutron spectrum remains constant.

5. Significance and Use

5.1 This practice is important in characterizing the radiation hardness of electronic devices irradiated by neutrons. This characterization makes it feasible to predict some changes in operational properties of irradiated semiconductor devices or electronic systems. To facilitate uniformity of the interpretation and evaluation of results of irradiations by sources of different fluence spectra, it is convenient to reduce the incident neutron fluence from a source to a single parameter—an equivalent monoenergetic neutron fluence—applicable to a particular semiconductor material.

5.2 In order to determine an equivalent monoenergetic neutron fluence, it is necessary to evaluate the displacement damage of the particular semiconductor material. Ideally, this quantity is correlated to the degradation of a specific functional performance parameter (such as current gain) of the semiconductor device or system being tested. However, this correlation has not been established unequivocally for all device types and performance parameters since, in many instances, other effects also can be important. Ionization effects produced by the incident neutron fluence or by gamma rays in a mixed neutron fluence, short-term and long-term annealing, and other factors can contribute to observed performance degradation (damage). Thus, caution should be exercised in making a correlation between calculated displacement damage and performance degradation of a given electronic device. The types of devices for which this correlation is applicable, and numerical evaluation of displacement damage are discussed in the annexes.

5.3 The concept of 1-MeV equivalent fluence is widely used in the radiation-hardness testing community. It has merits and disadvantages that have been debated widely (9-12). For these reasons, specifics of a standard application of the 1-MeV equivalent fluence are presented in the annexes.

6. Procedure for Calculating $\Phi_{eq,Eref,mat}$

6.1 To evaluate Eq 1 and 2, determine the energy limits E_{min} and E_{max} to be used in place of zero and infinity in the integrals of (Eq 1) and (Eq 2) and the values of the displacement damage function $F_{D,mat}$ (E) for the irradiated material and perform the indicated integrations.

6.1.1 Choose the upper limit E_{max} to be at an energy above which the integral damage falls to an insignificant level. For Godiva- or TRIGA-type spectra, this limit is about 12 MeV.

6.1.2 Choose the lower-energy limit E_{min} to be at an energy below which the integral damage falls to an insignificant level. For silicon irradiated by Godiva-type spectra, this energy has been historically chosen to be about 0.01 MeV. More highly moderated spectra may require lower thresholds or specialized filtering requirements such as a boron shield, or both.

6.1.3 The values of the neutron displacement damage function used in Eq 1 and 2 obviously depend on the material and the equivalent energy chosen. For silicon, resonance effects cause large variations (by a factor of 20 or more) in the displacement damage function as a function of energy over the range from about 0.1 to 8 MeV (4,5). Therefore, monoenergetic neutron sources with these energies may not be useful for effects testing. Also, for a selected equivalent energy, the value of F_{D,Eref,mat} at that specific energy may not be representative of the displacement damage function at nearby energies. In such cases, a method of averaging the damage function over a range of energies around the chosen equivalent energy can be used. Such averaging is discussed in the annexes. Because the $F_{D,mat}\left(E\right)$ term is normalized by dividing by $F_{D,Eref,mat}$ in Eq 1 and 2, only the shape of the $F_{D,mat}$ (E) function versus energy is of primary importance. In such a case, precise knowledge of the absolute values of F_{D.mat} (E) is not required in evaluating $\Phi_{eq,Eref,mat}$ and H_{mat} .

7. Determining $\Phi_{eq,Eref,mat}$ with a Monitor Foil

7.1 At the same time that the fluence spectrum, $\Phi(E)$, of the source is determined (for example, with an activation foil set in accordance with Guides E720 or E844E720E844, or both, and Test Method E721 or Practice E944, or both, place a fast-neutron monitor foil in the neutron field at an appropriate location. After $\Phi_{eq,Eref,mat}$ is determined and the monitor foil counted, calculate the ratio of the equivalent monoenergetic fluence to the unit monitor response, $\Phi_{eq,Eref,mat}/M_r$.

7.2 Use the response of the fast-neutron monitor foil, M_r , to predict $\Phi_{eq,Eref,mat}$ in subsequent routine device test irradiations. For this method to be valid, it is important to keep the source-foil geometry essentially identical to that used for calibrating the monitor foil. Moderate changes in source-to-foil distance are allowable. In addition, make sure the source location (of a Godiva-type reactor) with respect to scattering materials (walls, floor, etc.) is the same. Do not change or move nearby scattering materials or moderators.

7.3 Precautions in maintaining original calibration conditions are necessary to avoid altering the neutron fluence spectrum significantly in subsequent irradiations. An appreciable change in the spectrum will invalidate the calibration of the monitor foil and, therefore, would necessitate a new measurement of $\Phi(E)$ and recalibration of the monitor foil. Whenever the neutron source configuration is changed, as for example, if the core fuel elements are replaced or rearranged in a nuclear reactor, the activation foil spectrum measurements and all quantities derived from them may need to be remeasured.

7.4 The choice of a monitor foil material depends on several factors:

7.4.1 The activation threshold should be high enough so as to make it insensitive to neutrons below the E_{min} value used in Eq 1 and 2. However, the threshold energy should be low enough to sample a significant fraction of the total fluence.

7.4.2 The monitor foil should have a high neutron sensitivity and a convenient half-life.

7.4.3 The detector system available for counting the monitor foil may dictate the choice of foil material. A germanium gamma-ray detector system can be used, and ⁵⁴Fe or ⁵⁸Ni foils utilized as monitors. However, if a beta particle detector system is available, then ³²S foils are suitable. Details of the use of sulfur foils are given in Test Method E265.

8. Report

8.1 In the report of the results of radiation-hardness tests in which an equivalent monoenergetic neutron fluence is calculated, the report should include at least the following information:

8.1.1 Semiconductor material and device performance parameter (for example, current gain in silicon bipolar transistors) degradation being correlated to displacement damage should be specified.

8.1.2 Neutron source as to type and mode of operation during tests (fast-pulse or steady state).

8.1.3 Neutron fluence spectrum and how it was determined.

8.1.4 Monitor foil employed and the detector system used for counting the foil. If an effective fission cross section for the monitor foil is used, its value should be stated.

8.1.5 The neutron displacement damage function should be given, or referenced. The specific material (for example,

silicon) whose applicable damage function was used must be specified. The values cited in Annex A1 and Annex A2 shall be used for silicon and GaAs, respectively.

8.1.6 Methods used for determining the average value of $F_{D,Eref,mat}$ and the value of Eref selected. The values cited in Annex A1 and Annex A2 shall be used for silicon and GaAs, respectively.

8.1.7 Method used for evaluating the integrals of Eq 1 and 2 (for example, the energy bin width and number of bins in a numerical integration).

8.1.8 Values of $\Phi_{eq,Eref,mat}$, H _{mat}, and $\Phi_{eq,Eref,mat}/M_r$.

9. Precision and Bias

9.1 The precision in calculating $\Phi_{eq,Eref,mat}$ and H_{mat} will depend on the method of evaluation of the integrals in Eq 1 and 2 (for example, the width of the energy bins used in a numerical integration).

9.2 The uncertainty of the calculated results depends on (1) knowledge of the neutron fluence spectrum, (2) knowledge of the displacement damage functions over that energy spectrum, and (3) knowledge of the value of the average displacement damage function at the specified equivalent energy.

9.3 A specific example of the uncertainty associated with the calculation of a 1-MeV equivalent fluence for silicon is given in Annex A1.

10. Keywords

10.1 displacement damage; electronic hardness; gallium arsenide; hardness parameter; silicon; silicon damage; silicon equivalent damage (SED); 1–MeV equivalent fluence

ANNEXES

https://standards.iteh.ai/catalog/standards/sis(Mandatory Information) a-aa28-[9e3b2b(099b/astm-e722-09

A1. CALCULATION OF 1-MeV EQUIVALENT NEUTRON FLUENCE FOR SILICON

A1.1 Background

A1.1.1 The observable damage metric of interest in this annex is the change in gain of a silicon bipolar junction transistor (BJT) due to bulk displacement damage effects. The damage mechanism is the change in minority-carrier recombination lifetime in the bulk semiconductor material. While a BJT gain may also be degraded by oxide traps and interface states introduced by the ionizing dose to the oxide, this is a surface effect and is not within the scope of this standard. In interpreting measurements of this 1-MeV(Si) damage, efforts must be made to eliminate any interference from ionization-related surface effects.

A1.1.2 The choice of the specific energy for determining an equivalent fluence has been the subject of some controversy within the electronics hardness-testing community (9). Some workers (10) have proposed that 1 MeV be used while others (11 12) have suggested 14 MeV to be more appropriate. The concept of 1-MeV equivalent fluence has gained broad acception.

tance in practice, and procedures for applying it to silicon are described in this annex in some detail.

A1.1.3 An important basis of the practice is the correlation of radiation damage effects in a semiconductor device with the displacement kerma produced in bulk silicon by neutron irradiation. This correlation assumes that volume (versus surface) effects are the dominant radiation damage mechanism. Experimental evidence indicates that displacement kerma is a valid measure of device performance degradation (for example, reduction in current gain) in bipolar transistors whose operation basically depends on volume mechanisms (13, 14). However, for device types governed by surface phenomena (such as MOSFET devices), it is clear that this correlation is not valid. Surface-effect devices are more sensitive than are volume-effect devices to ionization radiation effects produced either by a neutron field or a mixed neutron-gamma field. Therefore, the basic mechanism associated with device performance and the effect being correlated (for example, gain degradation) should be kept in mind before applying this practice at any equivalent energy.

A1.2 Calculation of $\Phi_{eq,1MeV,Si}$

A1.2.1 The displacement damage function, $F_{D,mat}$ (E), defined for silicon in this annex is the silicon microscopic displacement kerma factor, as tabulated in Table A1.1.

A1.2.2 A 1-MeV equivalent fluence in silicon is defined for an irradiation by neutrons of any neutron spectrum for which the predominant source of displacement damage is from neutrons of energy between 10 keV and 20 MeV. The neutron fluence spectrum, $\Phi(E)$, may be that determined from a neutron transport calculation, that determined from measurements, or that given in an environment specification document.

A1.2.3 The neutron fluence spectrum, $\Phi(E)$, may be determined experimentally by measuring a set of activation foils and then by application of a spectral adjustment computer code (see Guide E720 and Test Method E721 for details).

A1.2.4 Results of calculations of silicon microscopic displacement kerma factors (displacement kerma per target atom per unit neutron fluence), K_{D,Si} (E), are given in Table A1.1 as a function of neutron energy over the range from 10^{-10} to 20 MeV (11, 15). The unit of the microscopic kerma factor is megaelectron volt times millibarns (MeV:mbarn). Each factor can be multiplied by 3.435×10^{-13} to convert to rad(Si):cm², or by 3.435×10^{-19} to convert to J-m²/kg or Gy(Si):m². The silicon microscopic displacement kerma factor as given in Table A1.1 is the accepted silicon damage function to be used in the application of this standard: $F_{D,Si}(E) = K_{D,Si}(E)$. This microscopic displacement kerma was computed by using the ENDF/B-VI²⁸Si cross section evaluation (18), a displacement threshold energy of 25 eV, the Robinson fit to the Lindhard energy partition function (19), and the NJOY97 processing code (20). Fig. A1.1 shows the energy dependence of the silicon 1-MeV damage function.

A1.2.5 An average value of neutron microscopic displacement kerma factor near 1 MeV is difficult to determine because of sharp neutron cross-section resonances in that energy region. To avoid these difficulties, Namenson, Wolicki, and Messenger (13) fitted the function AE(1 – exp(–B/E)) to various tabulations of κ_D (E) versus energy. The values of A and B obtained by a least squares fit yielded an average value at 1 MeV of 95 ± 4 MeV•mbarn. A similar procedure applied to the data given in Table A1.1 also gives a value close to 95 MeV•mbarn. Accordingly, the designated value of $F_{D,1MeV,Si}$ to be used in Eq 1 and 2 to calculate a 1-MeV equivalent fluence is 95 MeV•mbarn.

A1.2.6 For purposes of intercomparison of hardness testing results from various laboratories, the value of $F_{D,1MeV,Si}$ used in obtaining such results is very important; therefore, reporting of results should include confirmation that the value of $F_{D,1MeV,Si}$ designated in A1.2.5 was used in any calculation.

A1.2.7 Once the neutron fluence spectrum $\Phi(E)$ has been determined for the energy range of interest, then use numerical integration to evaluate Eq 1 and 2, using values for $F_D(E)$ from Table A1.1 and $F_{D.1MeV.Si} = 95$ MeV•mbarn.

Note A1.1—The damage function provided here differs from that in versions of this practice earlier than E722–93, and will result in a different value for $\Phi_{eq,1MeV,Si}$. For fast-burst and TRIGA reactors, the value calculated for $\Phi_{eq,1MeV,Si}$ will typically be 5 to 10 % lower than that calculated using E722–85.

A1.3 Precision and Bias

A1.3.1 The values for $\kappa_{D,Si}$ (E) given in Table A1.1 are determined by calculating the total kerma and then partitioning it into ionization and displacement fractions. Because of the lack of adequate theory to partition the kerma and uncertainties in cross sections, the estimated uncertainty in the microscopic displacement kerma factor is about 10 % up to 3 MeV. Correlation of displacement kerma with measured damage in many neutron fields has been confirmed with uncertainties no larger than 10 % (14).

A1.3.2 Uncertainties in the neutron fluence spectrum, $\Phi(E)$, will vary based on the method used to obtain it. If neutron sensors such as activation foils were used, see Standard Guide E721.

A1.3.3 Since this mandatory annex requires the use of Table A1.1 and $F_{D,1MeV,Si} = 95$ MeV•mbarn, no uncertainty in the calculation of 1-MeV equivalent fluence is attributable to the consistent use of these data. Therefore only the uncertainty in the determination of $\Phi(E)$ need be considered in assigning an uncertainty to the 1-MeV equivalent fluence. An uncertainty in the spectrum in the range ± 20 %, would most often lead to uncertainties no more than ± 10 % in the integral quantity $\Phi_{eq,1MeV,Si}$. While no specific group structure for representing the neutron fluence spectrum is recommended, the choice of energy bin boundaries will affect the uncertainty in the 1-MeV equivalent fluence. The energy bin boundaries should be chosen with due consideration for the shape of both the neutron spectrum and the 1-MeV equivalent damage function. A poor choice of the energy group structure used to evaluate the integral in Eq 2 could increase this uncertainty (see 8.1.7).

TABLE A1.1 Silicon Microscopic Displacement Kerma Factor

	Bin	Mid-Point Energy	Displacement Damage Function	
	#	(MeV)	(MeV•mbarn)	-
_	1	19.9500	182.8700	-
	2 3	19.8500 19.7500	183.0000 183.1200	
	4	19.6500	183.2500	
	5	19.5500 19.4500	183.3800 183.5100	
	7	19.3500	183.6300	
	8	19.2500	183.7500	
	10	19.1500	184.0000	
	11	18.9500	184.1100	
	12 13	18.8500 18.7500	184.2000 184.2800	
	14	18.6500	184.3700	
	15 16	18.5500	184.4500	
	17	18.3500	183.9700	
	18	18.2500	183.6200	
	19 20	18.1500 18.0500	183.2800 182.9400	
	21	17.9500	182.5900	
	22	17.8500	182.2400	
	23	17.6500	181.5800	
	25	17.5500	181.2400	
	26 27	17.4500 17.3500	180.6700 179.8800	
	28	17.2500	179.0800	
	29	17.1500	178.2800	
	31	16.9500	177.2400	
	32	16.8500	177.5000	
	33	16.6500	177.7600	
	35	16.5500	178.2700	
	36	16.4500	178.3200	
	38	16.2500	178.0300	
	39	A 16.1500 E722-09	177.8900	
	40 0 0/41	ndards/sist/15.9500)4e3-916	4-4fda_176.3000 9e3b21	
	42	15.8500	173.6300	
	43 44	15.6500	170.8600	
	45	15.5500	170.7200	
	46 47	15.4500 15.3500	170.5600	
	48	15.2500	170.2500	
	49 50	15.1500	170.0900	
	51	14.9500	169.7900	
	52	14.8500	169.6600	
	53 54	14.7500	169.5200	
	55	14.5500	169.2100	
	56 57	14.4500 14.3500	168.7300 167.9400	
	58	14.2500	167.1400	
	59 60	14.1500	166.3400	
	61	13.9500	165.4000	
	62	13.8500	165.8600	
	63 64	13.7500	166.2900	
	65	13.5500	167.1600	
	66 67	13.4500 13.3500	167.5300 167.8300	
	68	13.2500	168.1100	
	69 70	13.1500	168.3900	
	70	12.9500	168.6200	
				-

Bi	n Mid-Point Energy	Displacement Damage Function	
	(MeV)	(MeV•mbarn)	
7	2 12.8500	168.2800	
7	3 12.7500	167.9400	
7	4 12.6500	167.6000	
7	6 12.5500	167.2200	
7	7 12.3500	167.4700	
7	8 12.2500	167.7100	
/ 8	9 12.1500	167.9500 168.1700	
8	1 11.9500	165.6600	
8	2 11.8500	165.4600	
8	3 11.7500 11.6500	166.6200	
8	5 11.5500	168.6200	
8	6 11.4500	165.3800	
8	11.3500	166.0300	
8	8 11.2500	159.5200	
g	0 11.0500	158.7500	
9	1 10.9500	160.0500	
9	2 10.8500	162.9100	
9	3 10.7500 4 10.6500	159.0000	
g	5 10.5500	154.6000	
g	6 10.4500	154.7600	
9	7 10.3500	164.6700	
9	9 10.2500	163.3000	
10	0 0 10.0500	166.2100	
10	9.9500	164.4900	
	9.8500	164.0600	
	4 9.6500	156.1000	
10	5 9.5500	164.4100	
10	6 9.4500	169.8200	
10	8 9.2500	150.6900	
10	9 9.1500	153.8800	
11	0 9.0500 F72	174.5800	
	2 8 8500	177.5700	
nttps://standards.iten.ai/catalog/s	3 8.7500	146.7500	
11	4 8.6500	163.8600	
11	5 8.5500 6 8.4500	165.8300	
11	7 8.3500	162.0200	
11	8 8.2500	158.4200	
11	9 8.1500 9 8.0500	154.4300	
12	1 7.9500	186.4000	
12	2 7.8500	175.3400	
12	3 7.7500	174.8000	
12	4 7.6500 5 7.5500	162 9100	
12	6 7.4500	167.0500	
12	7 7.3500	168.4300	
12	8 7.2500	169.2700	
13	0 7.0500	161.1000	
13	6.9500	141.7700	
13	2 6.8500 6.7500	146.8900	
13	6.7500 4 6.6500	150.9200	
13	5 6.5500	119.2700	
13	6 6.4500	139.2700	
13	6.3500 6.3500	150.0900	
13	9 6.1500	127.7100	
14	0 6.0500	153.0000	
14	1 5.9500	137.1000	
14 14	2 5.8500 3 5.7500	164.7000 180.0500	
	- 0.7000		

-	Bin	Mid-Point Energy	Displacement Damage Function	
-	#	(MeV)	(MeV•mbarn)	
-	144	5.6500	152.0700	
	145	5.5500	145.6000	
	146	5.4500	116.9800	
	147	5.3500	120.1500	
	148	5.2500	145.7000	
	149	5.1500	170.3100	
	151	4 9500	145 5000	
	152	4.8500	160.6700	
	153	4.7500	185.6100	
	154	4.6500	158.6400	
	155	4.5500	138.3800	
	150	4.4500	134 8600	
	158	4.2500	164.4100	
	159	4.1500	108.7100	
	160	4.0500	131.6400	
	161	3.9500	134.3400	
	162	3.8500	108.8400	
	163	3.7500	69 52400	
	165	3.5500	111.2700	
	166	3.4500	119.0600	
	167	3.3500	113.8700	
	168	3.2500	118.0200	
	169	3.1500	131.5000	
	170	3.0500	120.2000	
	172	2.8500	135.0400	
	173	2.7500	106.9100	
	174	2.6500	115.6700	
	175	2.5500	131.1900	
	176	2.4500	102 8200	
	178	2.2500	105.4900	
	179	2.1500	106.9200	
	180	2.0500	95.21800	
	181	1.9500	129.4000	
	183	A 1 7500 E722	2-09 78.34200	
	184	1.6500	0164 464 163.0200 0 21-21-	
	185	1.5500	105.9800	
	186	1.4500	98.97900	
	187	1.3500	88.76000	
	189	1.1500	62.67300	
	190	1.0500	75.69200	
	191	0.98000	111.7900	
	192	0.94000	111.4900	
	193	0.90000	87.78100	
	194	0.88000	136 8000	
	196	0.78000	87.94400	
	197	0.74000	64.57500	
	198	0.70500	59.30200	
	199	0.67500	56.76700	
	200	0.64500	52,61800	
	202	0.58750	58.33400	
	203	0.56250	124.5500	
	204	0.53750	77.95800	
	205	0.51250	57.41600	
	206	0.48750	55.40500 53.50800	
	207	0.46250	52 65400	
	209	0.41250	51.89700	
	210	0.39000	52.10700	
	211	0.37000	49.72200	
	212	0.35000	50.09500	
	213	0.33000	49.20000 50.23700	
	215	0.29000	51.32600	

TABLE A1.1	Continued

Bin	Mid-Point Energ	y Displacement Damage Function	
 #	(MeV)	(MeV•mbarn)	
 216	0.27500	52.55800	
217	0.26250	54.95900	
210	0.24750	64.07300	
220	0.22500	69.75000	
221	0.21500	78.66700	
223	0.19500	111.2800	
224	0.18500	114.1000	
225	0.17500	64.49300	
220	0.15500	4.323200	
228	0.14625	1.350900	
229 230	0.13875	1.870700 2 552600	
231	0.12375	3.352800	
232	0.11750	3.982800	
233 234	0.11250 0.10750	4.431900 4.876000	
235	0.10250	5.197800	
236	0.98000E-01	5.417300	
237	0.94000E-01 0.90000E-01	5.611900	
239	0.86000E-01	6.040100	
240	0.82000E-01	6.185300	
241	0.74000E-01	6.595600	
243	0.70500E-01	6.831900	
244	0.67500E-01	7.178200	
245 246	0.64500E-01 0.61500E-01	7.992000	
247	0.58750E-01	11.45300	
248	0.56250E-01	47.95000	
250	0.51250E-01	- D 1.498700	
251	0.48750E-01	2.470200	
252 253	0.46250E-01 0.43750E-01	2.820300	
254	0.41250E-01	3.234200	
255	0.39000E-01	3.697700	
250	0.35000E-01	2.99164-4164 2.995800 0 2.949100	
258	0.33000E-01	2.823100	
259 260	0.31000E-01	2.689600	
261	0.23000E-01	2.452700	
262	0.26250E-01	2.363100	
263 264	0.24750E-01 0.23500E-01	2.261300 2.180800	
265	0.22500E-01	2.116100	
266	0.21500E-01	2.050100	
267 268	0.20500E-01 0.19500E-01	1.979200	
269	0.18500E-01	1.820900	
270 271	0.17500E-01	1.738500	
272	0.15500E-01	1.565500	
273	0.14625E-01	1.485300	
274 275	0.13875E-01 0.13125E-01	1.414100 1.342200	
276	0.12375E-01	1.270100	
277	0.11750E-01	1.210800	
278 279	0.11250E-01 0.10750E-01	1.165800	
280	0.10250E-01	1.076200	
281	0.98000E-02	1.036000	
282 283	0.94000E-02 0.90000E-02	0.9989800	
284	0.86000E-02	0.9232700	
285	0.82000E-02	0.8854100	
287	0.74000E-02	0.8096600	

TABLE A1.1	Continued

	Bin	Mid-Point Energ	y Displacement Damage Function	
-	#	(MeV)	(MeV•mbarn)	
-	288	0.70500E-02	0.7753600	
	289	0.67500E-02	0.7451400	
	290	0.61500E-02	0.6847000	
	292	0.58750E-02	0.6570400	
	293 294	0.56250E-02 0.53700E-02	0.6318600	
	295	0.51250E-02	0.5821900	
	296	0.48750E-02	0.6085100	
	297	0.46250E-02 0.43750E-02	0.5211400 0.4872300	
	299	0.41250E-02	0.4598900	
	300 301	0.39000E-02	0.4361800	
	302	0.35000E-02	0.3939900	
	303	0.33000E-02	0.3727900	
	304 305	0.31000E-02	0.3514300	
	306	0.27500E-02	0.3137700	
	307	0.26250E-02	0.3002000	
	308	0.24750E-02 0.23500E-02	0.2834300	
	310	0.22500E-02	0.2580800	
	311	0.21500E-02	0.2467900	
	312	0.20500E-02 0.19500E-02	0.2355000	
	314	0.18500E-02	0.2132400	
	315	0.17500E-02	0.2021500	
	310	0.15500E-02	0.1799600	
	318	0.14625E-02	0.1697200	
	319	0.13875E-02	0.1606400	
	321	0.12375E-02	0.1424900	
	322	0.11750E-02	0.1349500	
	323	0.11250E-02 0.10750E-02	0.1289000	
	325	0.10250E-02	0.1168000	
	326	0.98000E-03	0.1115900	
	328	0.90000E-03	0.1028000	
	329	0.86000E-03	0.98406E-01	
	330	0.82000E-03 0.78000E-03	0.89045E-01	
	332	0.74000E-03	0.83513E-01	
	333 334	0.70500E-03	0.78736E-01	
	335	0.64500E-03	0.72097E-01	
	336	0.61500E-03	0.68880E-01	
	337	0.58750E-03 0.56250E-03	0.65583E-01 0.62205E-01	
	339	0.53750E-03	0.58827E-01	
	340	0.51250E-03	0.55449E-01	
	342	0.46250E-03	0.47534E-01	
	343	0.43750E-03	0.43386E-01	
	344 345	0.41250E-03 0.39000E-03	0.39238E-01 0.36301F-01	
	346	0.37000E-03	0.34546E-01	
	347	0.35000E-03	0.32464E-01	
	348 349	0.33000E-03	0.24134E-01	
	350	0.29000E-03	0.20712E-01	
	351 352	0.27500E-03	0.18816E-01 0.17222E-01	
	353	0.24750E-03	0.14956E-01	
	354	0.23500E-03	0.12137E-01	
	355 356	0.22500E-03 0.21500E-03	0.98052E-02 0.74733E-02	
	357	0.20500E-03	0.51414E-02	
	358	0.19500E-03	0.34199E-02	
	228	0.18500E-03	U.229/9E-U2	